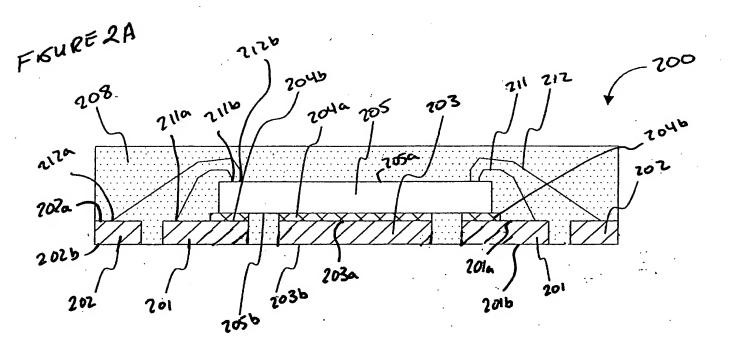
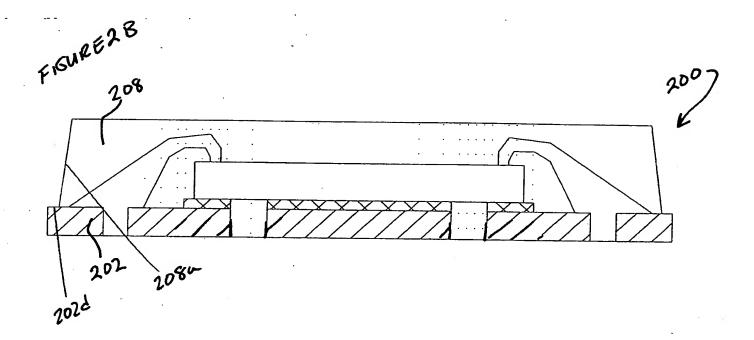
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PRIOR ART FIGURE 1 ENCAPSULANT WIRE CHIP 14 LEAD DIEPAD LEAD

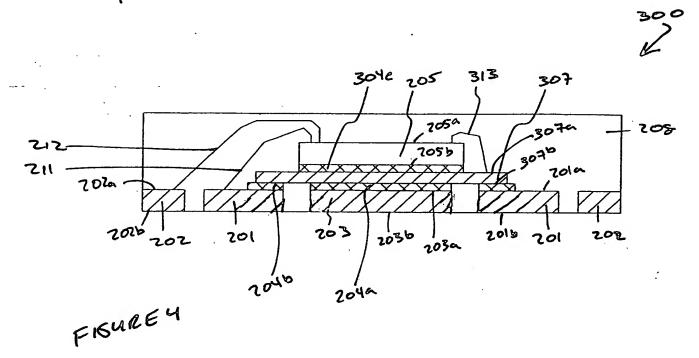


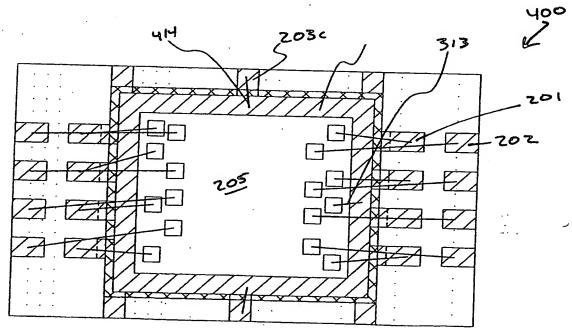
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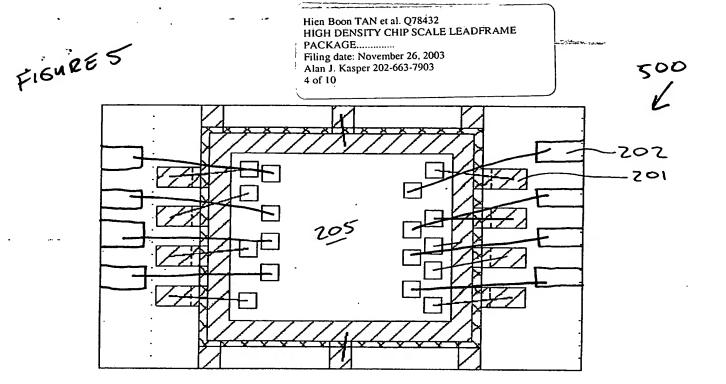


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FIGURES







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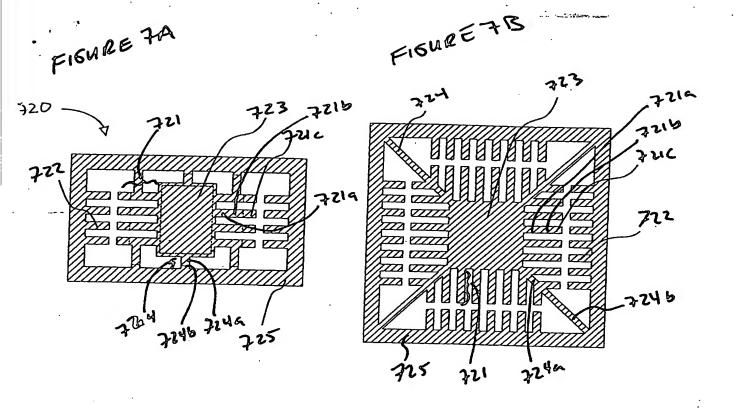
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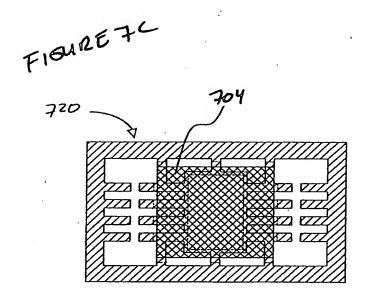
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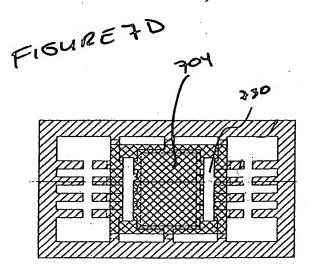
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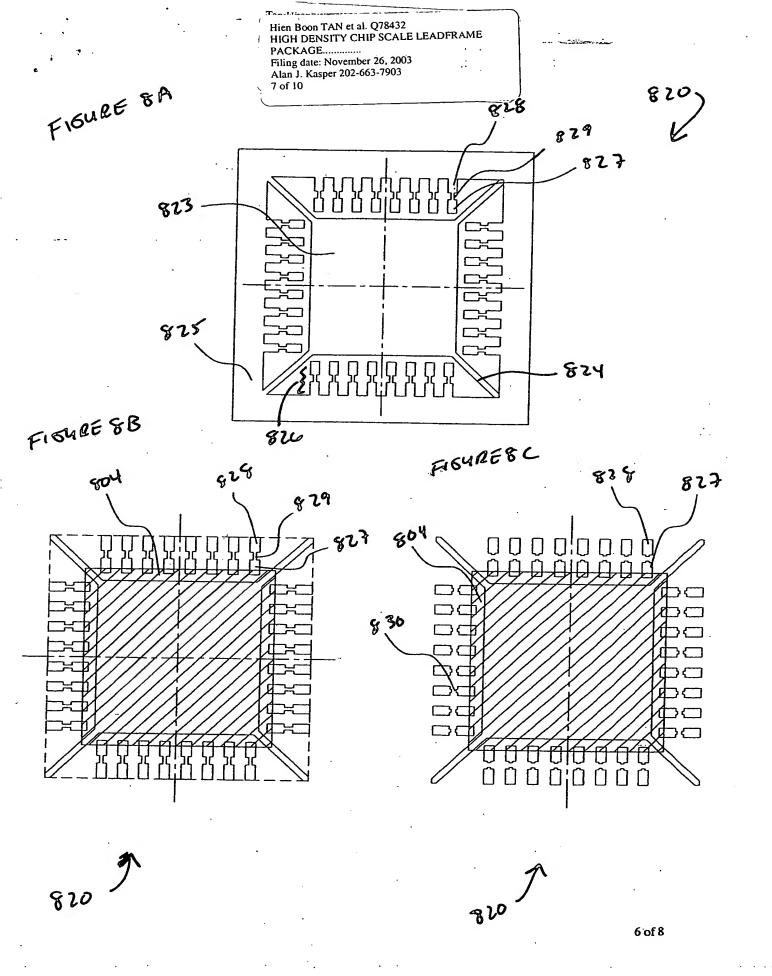






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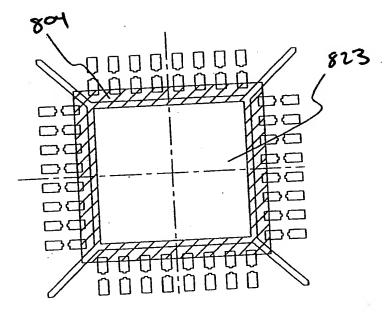
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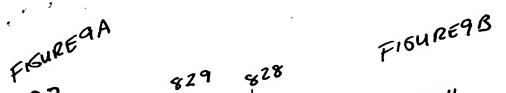


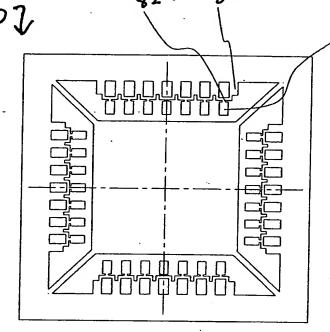
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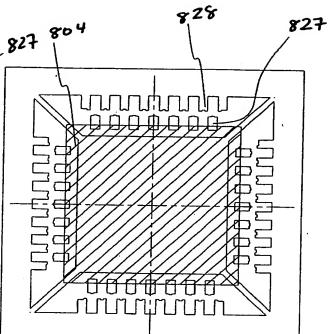
FIGURE 8D

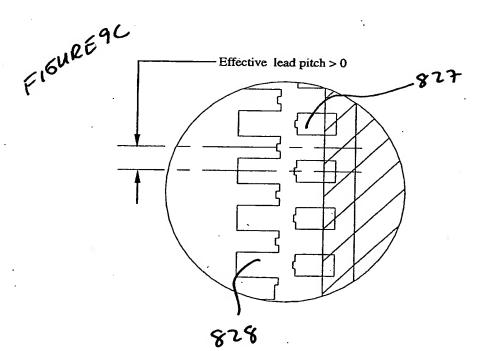
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